

/ Descriptions

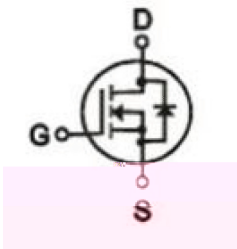
x

/ Features

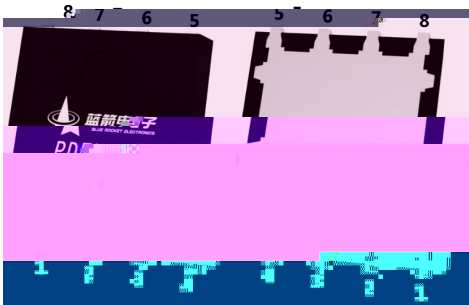
≤

/ Applications

/ Equivalent Circuit

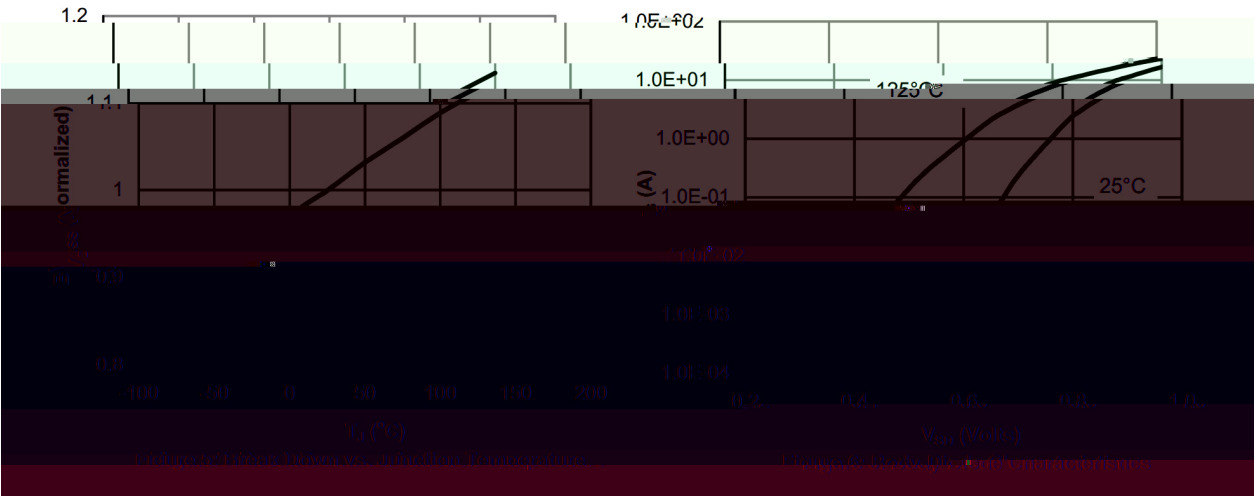
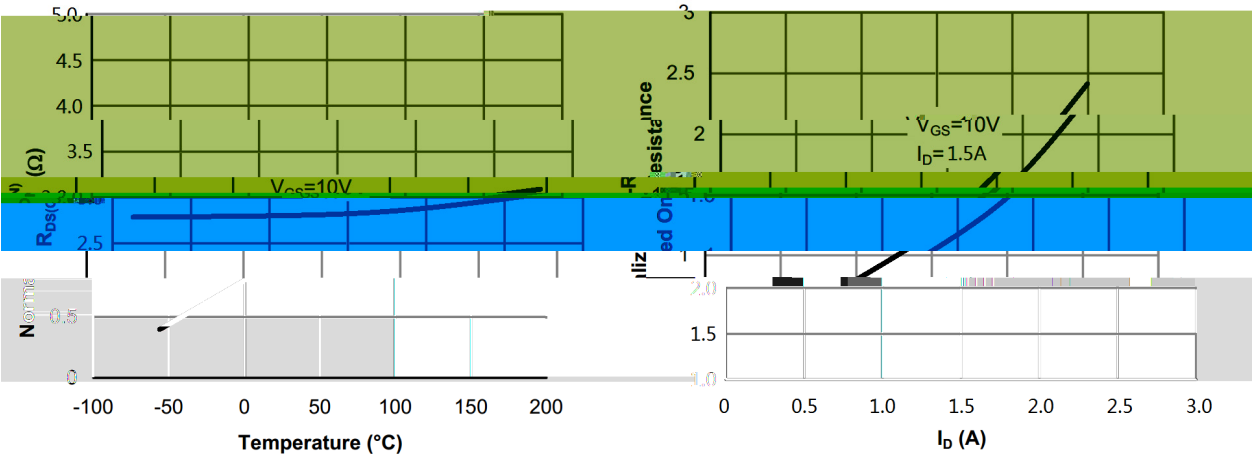
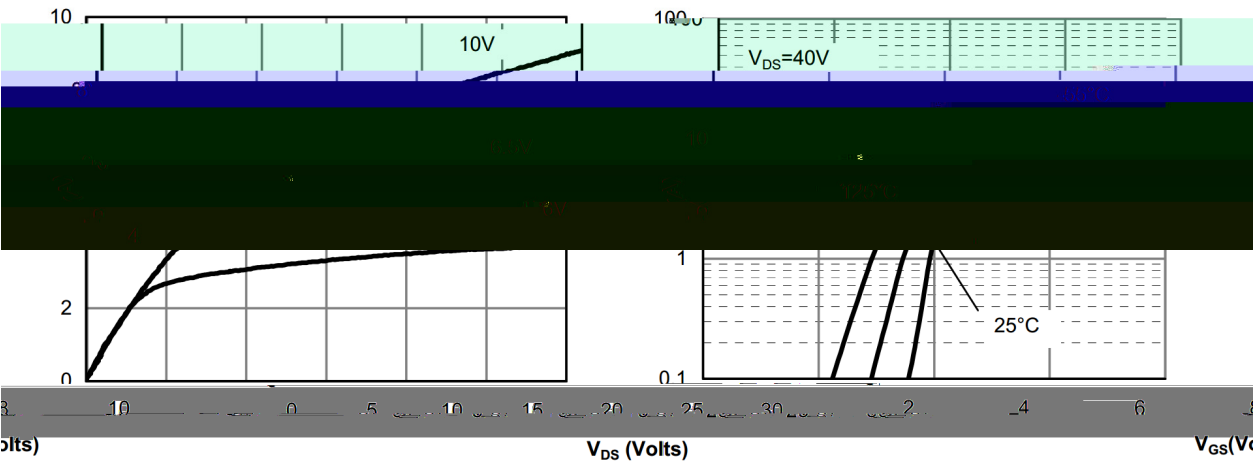


/ Pinning



/ Marking

/ Electrical Characteristic Curve



/ Electrical Characteristic Curve

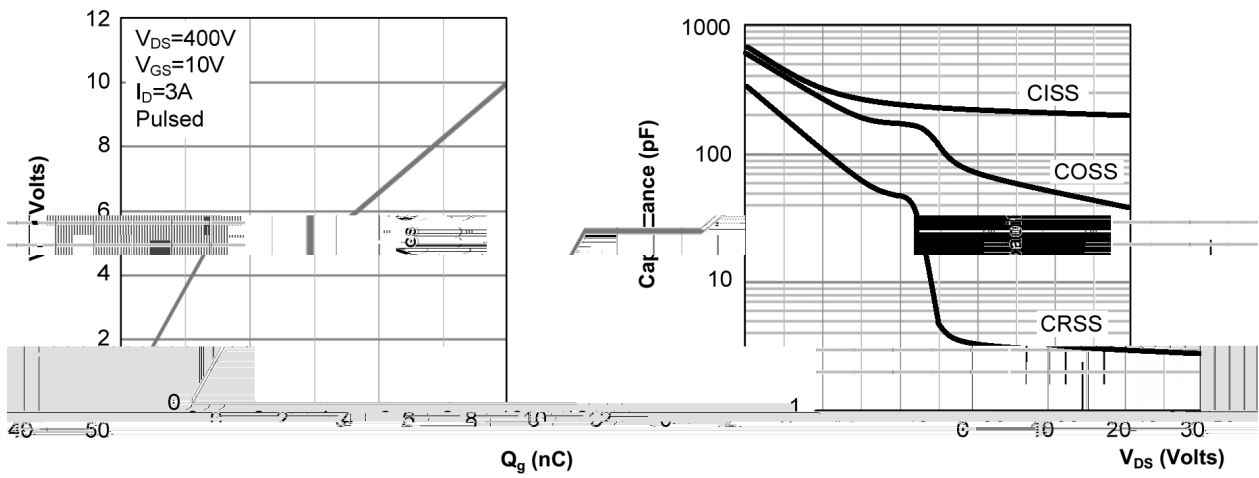


Figure 8: Capacitance Characteristics

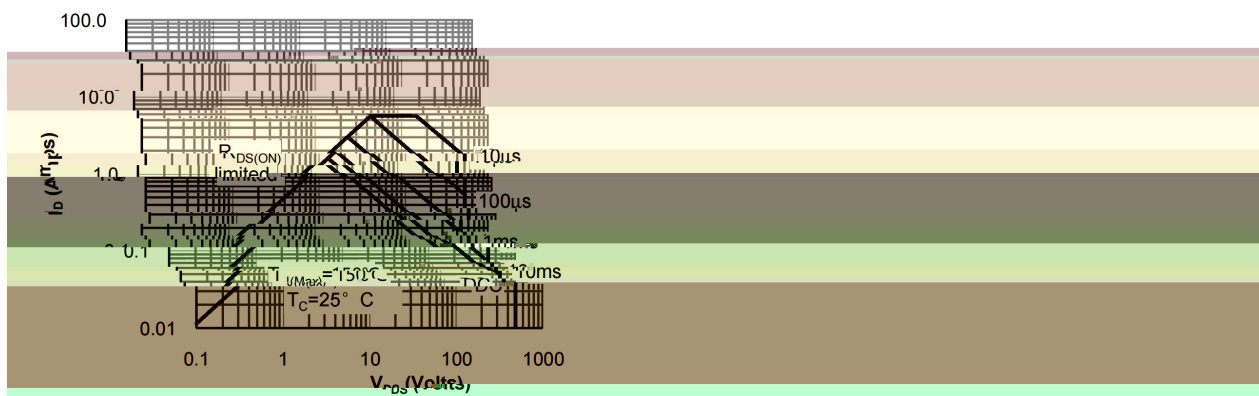


Figure 9: Maximum Forward Biased Safe Operating Area

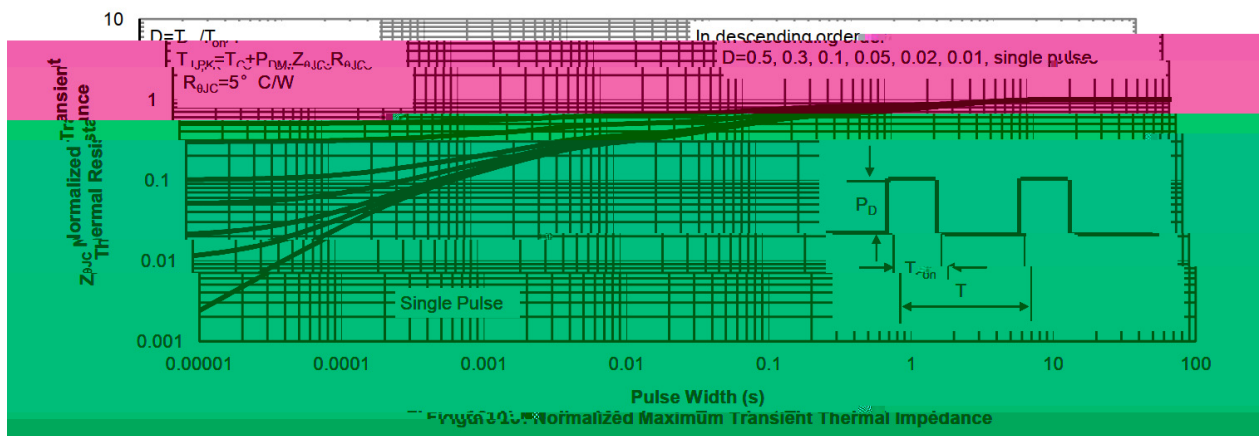
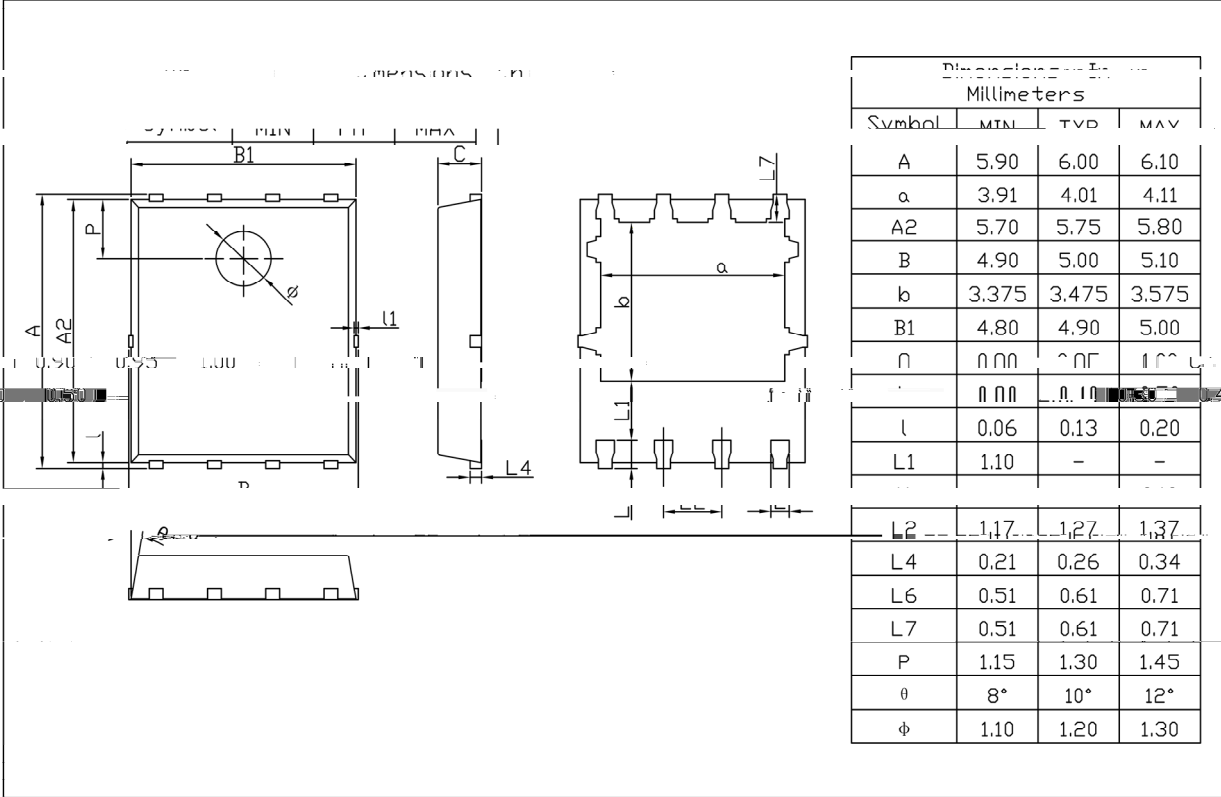


Figure 10: Normalized Maximum Transient Thermal Impedance

Package Dimensions

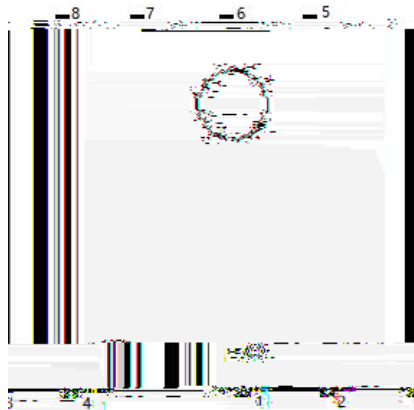
PDFN5 X6

Unit:mm



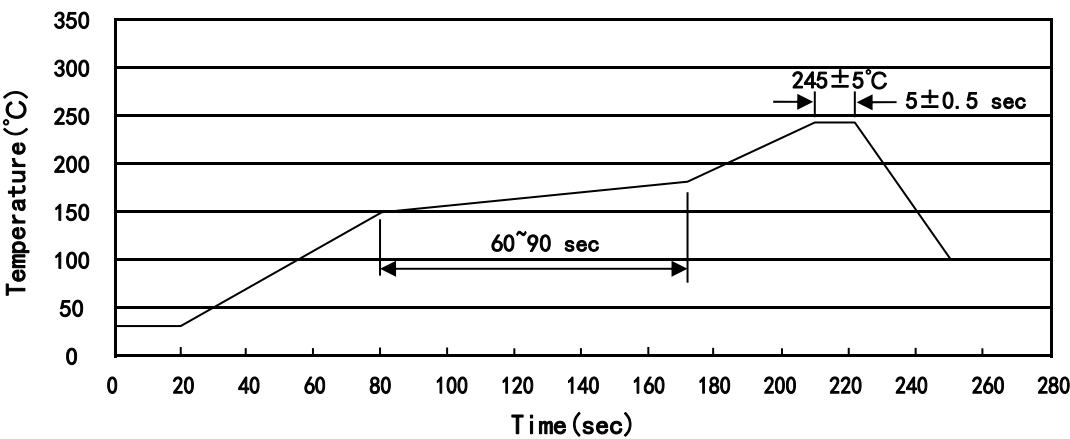
Rev.01 202209

/ Marking Instructions



BR

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box

/ Notices